

Integrated Device Technology, Inc.

## HIGH-SPEED BiCMOS ECL STATIC RAM 64K (64K x 1-BIT) SRAM

IDT10490  
IDT100490  
IDT101490

### FEATURES:

- 65,536-words x 1-bit organization
- Address access time: 8/10/12/15
- Low power dissipation: 420mW (typ.)
- Guaranteed Output Hold time
- Fully compatible with ECL logic levels
- Separate data input and output
- JEDEC standard through-hole and surface mount packages

### DESCRIPTION:

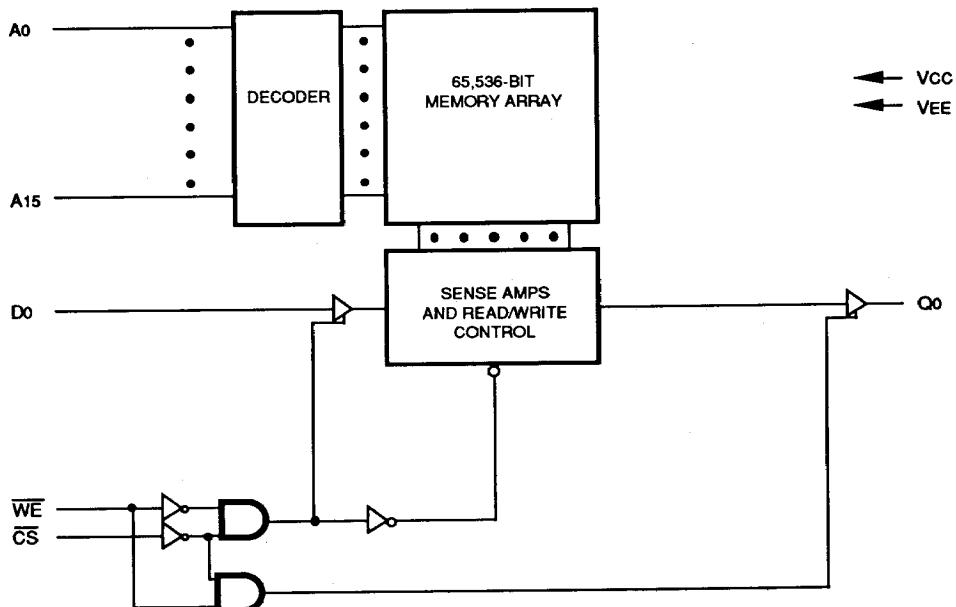
The IDT10490, IDT100490 and IDT101490 are 65,536-bit high-speed BiCEMOS™ ECL static random access memories organized as 64K x 1, with separate data inputs and outputs. All I/Os are fully compatible with ECL levels.

These devices are part of a family of asynchronous one-bit-wide ECL SRAMs. The devices have been configured to follow the standard ECL SRAM JEDEC pinout. Because they are manufactured in BiCEMOS™ technology, however, power dissipation is greatly reduced over equivalent bipolar devices.

The asynchronous SRAMs are the most straightforward to use because no additional clocks or controls are required: DataOUT is available an access time after the last change of address. To write data into the device requires the creation of a Write Pulse, and the write cycle disables the output pins in conventional fashion.

The fast access time and guaranteed Output Hold time allow greater margin for system timing variation. DataIN setup time specified with respect to the trailing edge of Write Pulse eases write timing allowing balanced Read and Write cycle times.

### FUNCTIONAL BLOCK DIAGRAM



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**COMMERCIAL TEMPERATURE RANGE**

**SEPTEMBER 1990**

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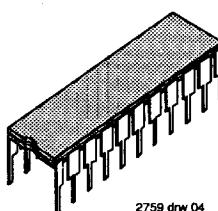
DSC-8001/2

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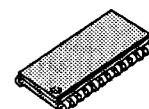
## PIN CONFIGURATION

Q0	1	22	Vcc
A0	2	21	D0
A1	3	20	CS
A2	4	19	WE
A3	5	18	A15
A4	6	17	A14
A5	7	16	A13
A6	8	15	A12
A7	9	14	A11
A8	10	13	A10
VEE	11	12	A9

2759 dw 02

CERDIP  
TOP VIEW

2759 dw 04



2759 dw 05

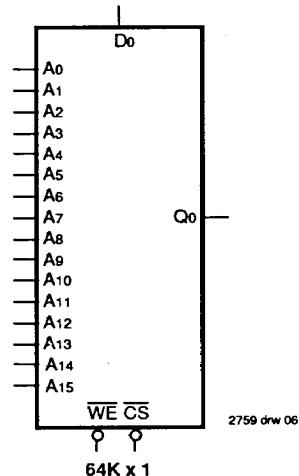
300-Mil-Wide  
CERDIP PACKAGE  
D22300-Mil-Wide  
PLASTIC SOJ PACKAGE  
Y24

Q0	1	24	Vcc
A0	2	23	D0
A1	3	22	CS
A2	4	21	WE
A3	5	20	NC
A4	6	19	A15
A5	7	18	A14
A6	8	17	A13
A7	9	16	A12
A8	10	15	A11
NC	11	14	A10
VEE	12	13	A9

2759 dw 03

SOJ  
TOP VIEW

## LOGIC SYMBOL



## PIN DESCRIPTIONS

Symbol	Pin Name
A0 through A15	Address Inputs
D0	Data Input
Q0	Data Output
WE	Write Enable Input
CS	Chip Select Input (Internal pull down)
VEE	More Negative Supply Voltage
Vcc	Less Negative Supply Voltage

2759 b1 01

CAPACITANCE ( $T_A = +25^\circ\text{C}$ ,  $f=1.0\text{MHz}$ )

Symbol	Parameter	DIP		SOJ		Unit
		Typ.	Max.	Typ.	Max.	
CIN	Input Capacitance	4	-	3	-	pF
COUT	Output Capacitance	6	-	3	-	pF

2759 b1 03

AC OPERATING RANGES<sup>(1)</sup>

I/O	VEE	Temperature
10K	$-5.2V \pm 5\%$	0 TO $75^\circ\text{C}$ , air flow exceeding 2 m/sed
100K	$-4.5V \pm 5\%$	0 TO $85^\circ\text{C}$ , air flow exceeding 2 m/sed
101K	-4.75V to -5.46V	0 TO $75^\circ\text{C}$ , air flow exceeding 2 m/sed

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NOTE:

1. Referenced to Vcc

TRUTH TABLE<sup>(1)</sup>

CS	WE	Data OUT	Function
H	X	L	Deselected
L	H	RAM Data	Read
L	L	L	Write

2759 b1 04

NOTE:  
1. H=High, L=Low, X=Don't Care

### ECL-10K ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Symbol	Rating		Value	Unit
VTERM	Terminal Voltage With Respect to GND		+0.5 to -7.0	V
TA	Operating Temperature		0 to +75	°C
TBIAS	Temperature Under Bias		-55 to +125	°C
TSTG	Storage Temperature	Ceramic Plastic	-65 to +150 -55 to +125	°C
PT	Power Dissipation		1.5	W
IOUT	DC Output Current (Output High)		-50	mA

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NOTE:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

### ECL-10K DC ELECTRICAL CHARACTERISTICS

(VEE = -5.2V, RL = 50Ω to -2.0V, TA = 0 to +75°C, air flow exceeding 2 m/sec)

Symbol	Parameter	Test Conditions		Min. (B)	Typ. <sup>(1)</sup>	Max. (A)	Unit	TA
VOH	Output HIGH Voltage	V IN = V IH A or V IL B		-1000 -960 -900	-885	-840 -810 -720	mV	0°C 25°C 75°C
VOL	Output LOW Voltage	V IN = V IH A or V IL B		-1870 -1850 -1830	—	-1665 -1650 -1625	mV	0°C 25°C 75°C
VOHC	Output Threshold HIGH Voltage	V IN = V IH B or V IL A		-1020 -980 -920	—	—	mV	0°C 25°C 75°C
VOLC	Output Threshold LOW Voltage	V IN = V IH B or V IL A		—	—	-1645 -1630 -1605	mV	0°C 25°C 75°C
VIH	Input HIGH Voltage	Guaranteed Input Voltage High for All Inputs		-1145 -1105 -1045	—	-840 -810 -720	mV	0°C 25°C 75°C
VIL	Input LOW Voltage	Guaranteed Input Voltage Low for All Inputs		-1870 -1850 -1830	—	-1490 -1475 -1450	mV	0°C 25°C 75°C
IIH	Input HIGH Current	V IN = V IH A	CS	—	—	220	μA	—
IIH			Others	—	—	110	μA	—
ILL	Input LOW Current	V IN = V IL B	CS	0.5	—	170	μA	—
ILL			Others	-50	—	90	μA	—
IEE	Supply Current	All Inputs and Outputs Open		-170	-80	—	mA	—

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NOTES:

- Typical parameters are specified at VEE = -5.2V, TA = +25°C and maximum loading.

### ECL-100K ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Symbol	Rating	Value	Unit
VTERM	Terminal Voltage With Respect to GND	+0.5 to -7.0	V
TA	Operating Temperature	0 to +85	°C
TBIAS	Temperature Under Bias	-55 to +125	°C
TSTG	Storage Temperature	-65 to +150 -55 to +125	°C
PT	Power Dissipation	1.5	W
IOUT	DC Output Current (Output High)	-50	mA

NOTE: 2759tbl07

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

### ECL-100K DC ELECTRICAL CHARACTERISTICS

(VEE = -4.5V, RL = 50Ω to -2.0V, TA = 0 to +85°C, air flow exceeding 2 m/sec)

Symbol	Parameter	Test Conditions	Min. (B)	Typ. <sup>(1)</sup>	Max. (A)	Unit
VOH	Output HIGH Voltage	V IN = V IHA or V ILB	-1025	-955	-880	mV
VOL	Output LOW Voltage	V IN = V IHA or V ILB	-1810	-1715	-1620	mV
VOHC	Output Threshold HIGH Voltage	V IN = V IHB or V ILA	-1035	—	—	mV
VOLC	Output Threshold LOW Voltage	V IN = V IHB or V ILA	—	—	-1610	mV
VIH	Input HIGH Voltage	Guaranteed Input Voltage High for All Inputs	-1165	—	-880	mV
VIL	Input LOW Voltage	Guaranteed Input Voltage Low for All Inputs	-1810	—	-1475	mV
IIH	Input HIGH Current	V IN = V IHA	CS Others	— —	220 110	µA
IIL	Input LOW Current	V IN = V ILB	CS Others	0.5 -50	170 90	µA
IEE	Supply Current	All Inputs and Outputs Open	-150	-70	—	mA

2759tbl08

NOTE:

- Typical parameters are specified at VEE = -4.5V, TA = +25°C and maximum loading.

### ECL-101K ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Symbol	Rating		Value	Unit
VTERM	Terminal Voltage With Respect to GND		+0.5 to -7.0	V
TA	Operating Temperature		0 to +75	°C
TBIAS	Temperature Under Bias		-55 to +125	°C
TSTG	Storage Temperature	Ceramic Plastic	-65 to +150 -55 to +125	°C
PT	Power Dissipation		1.0	W
IOUT	DC Out input Current (Output High)		-50	mA

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NOTE:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

### ECL-101K DC ELECTRICAL CHARACTERISTICS

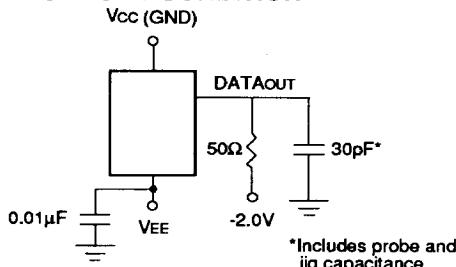
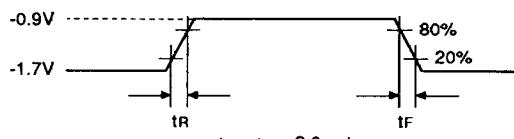
(VEE = -5.2V, RL = 50Ω to -2.0V, TA = 0 to +75°C, air flow exceeding 2 m/sec)

Symbol	Parameter	Test Conditions		Min. (B)	Typ. <sup>(1)</sup>	Max. (A)	Unit
VOH	Output HIGH Voltage	V IN = V IH A or V IL B		-1025	-955	-880	mV
VOL	Output LOW Voltage	V IN = V IH A or V IL B		-1810	-1715	-1620	mV
VOHC	Output Threshold HIGH Voltage	V IN = V IH B or V IL A		-1035	—	—	mV
VOCL	Output Threshold LOW Voltage	V IN = V IH B or V IL A		—	—	-1610	mV
VIH	Input HIGH Voltage	Guaranteed Input Voltage High for All Inputs		-1165	—	-880	mV
VIL	Input LOW Voltage	Guaranteed Input Voltage Low for All Inputs		-1810	—	-1475	mV
I IH	Input HIGH Current	V IN = V IH A	CS	—	—	220	μA
			Others	—	—	110	
I IL	Input LOW Current	V IN = V IL B	CS	0.5	—	170	μA
			Others	-50	—	90	
IEE	Supply Current	All Inputs and Outputs Open		-170	-80	—	mA

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NOTE:

- Typical parameters are specified at VEE = -5.2V, TA = +25°C and maximum loading.

**AC TEST LOAD CONDITION****AC TEST INPUT PULSE**

Note: All timing measurements are referenced to 50% input levels.

2759 dw 07

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**RISE/FALL TIME**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
$t_R$	Output Rise Time	-	-	2	-	ns
$t_F$	Output Fall Time	-	-	2	-	ns

2759 dl 11

**FUNCTIONAL DESCRIPTION**

The IDT10490, IDT100490 and IDT101490 BiCMOS ECL static RAMs (SRAM) provide high speed with low power dissipation typical of BiCMOS ECL. These devices follow the conventional pinout and functionality for 64Kx1 SRAMs. The ECL-101K meets electrical specifications that combine the ECL-100K temperature and voltage compensated output levels with the high-speed of ECL-10K VEE compatibility (-5.2V).

**READ TIMING**

The read timing on these asynchronous devices is straightforward. DataOUT is held low until the device is selected by Chip Select ( $\overline{CS}$ ). Then Address (ADDR) settles and data appears on the output after time  $t_{AA}$ . Note that DataOUT is held for a short time ( $t_{OH}$ ) after the address begins to change for the next access, then ambiguous data is on the bus until a new time  $t_{AA}$ .

**WRITE TIMING**

To write data to the device, a Write Pulse need be formed on the Write Enable input ( $\overline{WE}$ ) to control the write to the SRAM array. While  $\overline{CS}$  and ADDR must be set-up when  $\overline{WE}$  goes low, DataIN can settle after the falling edge of  $\overline{WE}$ , giving the data path extra margin. Data is written to the memory cell at the end of the Write Pulse, and addresses and Chip Select must be held after the rising edge of the Write Pulse to ensure satisfactory completion of the cycle.

DataOUT is disabled (held low) during the Write Cycle. If  $\overline{CS}$  is held low (active) and addresses remain unchanged, the DataOUT pins will output the written data after "Write Recovery Time" ( $t_{WR}$ ).

Because of the very short Write Pulse requirement, these devices can be cycled as quickly for Writes as for Reads. Balanced cycles mean simpler timing in cache applications.

**AC ELECTRICAL CHARACTERISTICS** (Over the AC Operating Range)

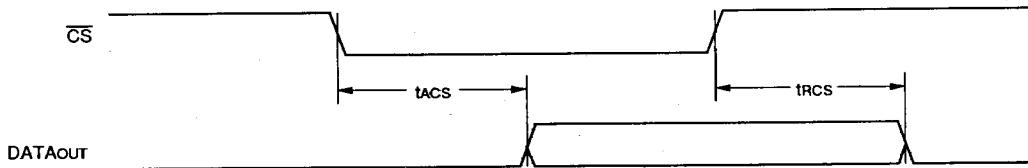
Symbol	Parameter <sup>(1)</sup>	Test Condition	10490S8		10490S10		10490S12		10490S15		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
<b>Read Cycle</b>											
tACS	Chip Select Access Time	—	—	3	—	5	—	5	—	5	ns
tRCS	Chip Select Recovery Time	—	—	3	—	5	—	5	—	5	ns
tAA	Address Access Time	—	—	8	—	10	—	12	—	15	ns
tOH	Data Hold from Address Change	—	3	—	3.5	—	3.5	—	3.5	—	ns

**NOTES:**

1. Input and Output reference level is 50% point of waveform.

2759 I&W 12

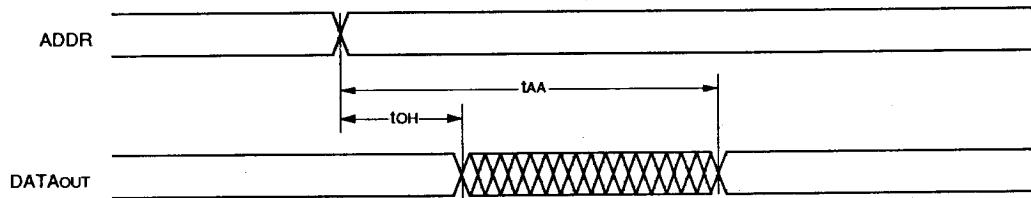
**READ CYCLE GATED BY CHIP SELECT**



2759 drw 09

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**READ CYCLE GATED BY ADDRESS**



2759 drw 10

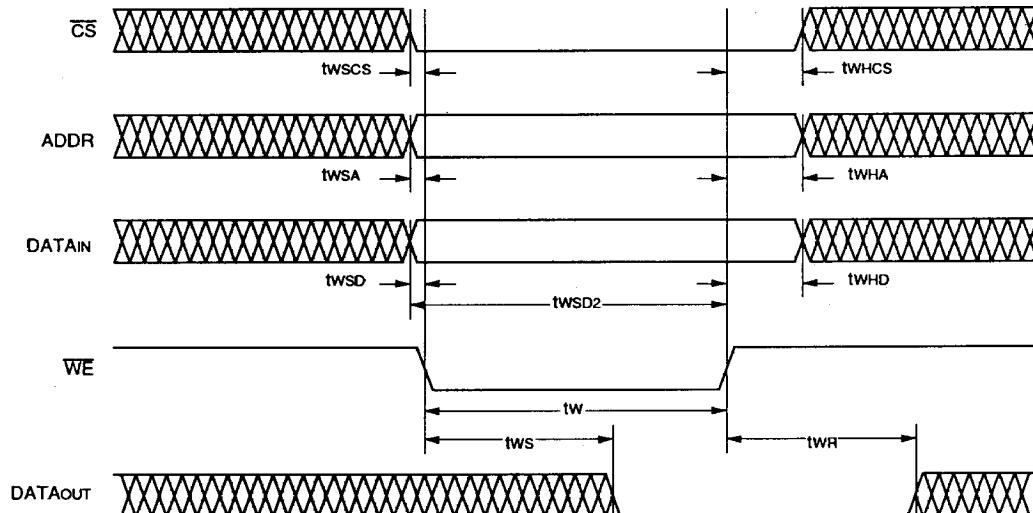
**AC ELECTRICAL CHARACTERISTICS** (Over the AC Operating Range)

Symbol	Parameter <sup>(1)</sup>	Test Condition	10490S8		10490S10		10490S12		10490S15		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
<b>Write Cycle</b>											
t <sub>W</sub>	Write Pulse Width	t <sub>WSA</sub> = minimum	6	—	8	—	10	—	10	—	ns
t <sub>WSD</sub>	Data Set-up Time	—	0	—	0	—	0	—	2	—	ns
t <sub>WSD2</sub> <sup>(2)</sup>	Data Set-up Time to WE High	—	5	—	5	—	5	—	5	—	ns
t <sub>WSA</sub>	Address Set-up Time	t <sub>WSA</sub> = minimum	0	—	0	—	0	—	2	—	ns
t <sub>WSCS</sub>	Chip Select Set-up Time	—	0	—	0	—	0	—	2	—	ns
t <sub>WHD</sub>	Data Hold Time	—	2	—	2	—	2	—	3	—	ns
t <sub>WHA</sub>	Address Hold Time	—	2	—	2	—	2	—	3	—	ns
t <sub>WHCS</sub>	Chip Select Hold Time	—	2	—	2	—	2	—	3	—	ns
t <sub>WS</sub>	Write Disable Time	—	—	5	—	5	—	5	—	10	ns
t <sub>WR</sub> <sup>(3)</sup>	Write Recovery Time	—	—	10	—	12	—	14	—	18	ns

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- NOTES:
1. Input and Output reference level is 50% point of waveform.
  2. t<sub>WSD</sub> is specified with respect to the falling edge of WE for compatibility with bipolar part specifications, but this device actually only requires t<sub>WSD2</sub> with respect to rising edge of WE.
  3. t<sub>WR</sub>=t<sub>WHA</sub> + t<sub>AA</sub> and thus can include a full access time if addresses change while Chip Select is still low.

**WRITE CYCLE TIMING DIAGRAM**



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## ORDERING INFORMATION

IDT	XXX	X	XX	X	Process/ Temp. Range	
Device Type	Architecture	Speed	Package			
				Blank	Commercial 0°C to +75°C	
				D	CERDIP	
				Y	Plastic SOJ	
		8				
		10				
		12				
		15				
				S	Standard Architecture	
				10490	64K (64K x 1-bit) BiCMOS ECL-10K Static RAM	
				100490	64K (64K x 1-bit) BiCMOS ECL-100K Static RAM	
				101490	64K (64K x 1-bit) BiCMOS ECL-101K Static RAM	

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